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Docket No.: YOR920000578US1
(PATENT)

OFFICIAL

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Panayotis Andricacos, et al

Application No.: 09/760,884

Group Art Unit: 1741

Filed: January 17, 2001

Examiner: Smith Hicks

For: TUNGSTEN ENCAPSULATED COPPER
INTERCONNECTIONS USING
ELECTROPLATING

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This is in response to the Office Action dated October 9, 2003.

Amendments to the Specification begin on page 2 of this paper;

Amendments to the Claims begin on page 3 of this paper;

Remarks and Arguments begin on page 5 of this paper.